

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4018848

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHINICHI WATANUKI	07/29/2016
AKIRA MITSUIKI	08/02/2016
ATSURO INADA	08/01/2016
TOHRU MOGAMI	07/21/2016
TSUYOSHI HORIKAWA	07/21/2016
KEIZO KINOSHITA	07/22/2016

RECEIVING PARTY DATA

Name:	RENESAS ELECTRONICS CORPORATION
Street Address:	2-24, TOYOSU 3-CHOME, KOUTOU-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	135-0061
Name:	PHOTONICS ELECTRONICS TECHNOLOGY RESEARCH ASSOCIATION
Street Address:	1-20-10, SEKIGUCHI, BUNKYO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	112-0014

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15243746

CORRESPONDENCE DATA

Fax Number: (703)761-2375

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: MCGINN I.P. LAW GROUP, PLLC

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Address Line 4: VIENNA, VIRGINIA 22182-3817

ATTORNEY DOCKET NUMBER:	TSUT.024
NAME OF SUBMITTER:	SEAN M. MCGINN
SIGNATURE:	/Sean M. McGinn/
DATE SIGNED:	08/23/2016
Total Attachments: 4 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif	

ASSIGNMENT
(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, and Photonics Electronics Technology Research Association, a corporation organized under the laws of Japan, located at 2-24, Toyosu 3-chome, Koutou-ku, Tokyo 135-0061, Japan, and 1-20-10, Sekiguchi, Bunkyo-ku, Tokyo 112-0014, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, and Photonics Electronics Technology Research Association, their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation, and Photonics Electronics Technology Research Association, their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignees;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation, and Photonics Electronics Technology Research Association.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Shinichi Watanuki</u> (Shinichi WATANUKI)	<u>July 29, 2016</u>
2) _____ (Akira MITSUIKI)	_____
3) _____ (Atsuro INADA)	_____
4) _____ (Tohru MOGAMI)	_____
5) _____ (Tsuyoshi HORIKAWA)	_____
6) _____ (Keizo KINOSHITA)	_____

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INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ (Shinichi WATANUKI)	_____
2) <u>Akira Mitsuiiki</u> (Akira MITSUIKI)	<u>August 2, 2016</u>
3) _____ (Atsuro INADA)	_____
4) _____ (Tohru MOGAMI)	_____
5) _____ (Tsuyoshi HORIKAWA)	_____
6) _____ (Keizo KINOSHITA)	_____

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1) _____ (Shinichi WATANUKI)	_____
2) _____ (Akira MITSUIKI)	_____
3) <u>Aisuro Inada</u> _____ (Aisuro INADA)	<u>August 1, 2016</u>
4) _____ (Tohru MOGAMI)	_____
5) _____ (Tsuyoshi HORIKAWA)	_____
6) _____ (Keizo KINOSHITA)	_____

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2) _____ (Akira MITSUIKI)	_____
3) _____ (Atsuro INADA)	_____
4) <u>John Mogami</u> (Tohru MOGAMI)	July 21, 2016
5) <u>Tsuyoshi Horikawa</u> (Tsuyoshi HORIKAWA)	July 21, 2016
6) <u>Keizo Kinoshita</u> (Keizo KINOSHITA)	July 22, 2016